

16A

Data Sheet SMT-0540-S-2-EB-R

PUI Audio's 5x5mm **SMT-0540-S-2-R** outputs loud sound in a side-firing package for use in thin electronics.

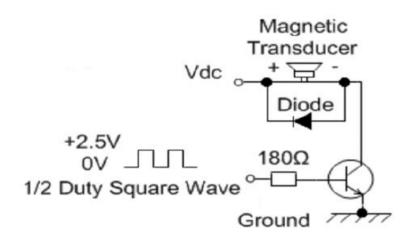
The **SMT-0540-S-2-EB-R** makes it simple to test, or even integrate, this transducer without spinning-up your own PCB.

Specifications

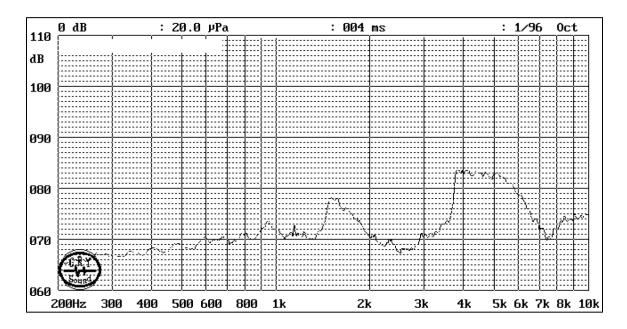
Parameters	Values	Units
Rated Voltage	3	V0-p
Operating Voltage Range	2~4	V0-p
Current Draw at Rated Voltage*	90	mA
Coil Resistance	17 ±3	Ohms
Minimum SPL @ 10cm*	78	dBA
Resonant Frequency	4,000 ±500	Hz
Housing Material	LCP	-
Terminal Material	Tin-Plated Brass	-
Weight	0.1	Grams
Acceptable Soldering Methods	Hand Solder @ 350C for 5s, Reflow Solder	See page 3 for reflow solder information
Environmental Compliances	RoHS/REACH	-
Operating Temperature	-40 ∼ +85	°C
Storage Temperature	-40 ~ +85	°C

^{*}At rated voltage with 50% duty cycle 4 kHz positive biased square-wave

Recommended Drive Circuit (Transistor should have a Vce \leq 0.15V and hFE \geq 200)



Typical Frequency Response (3V input measured at 10cm)

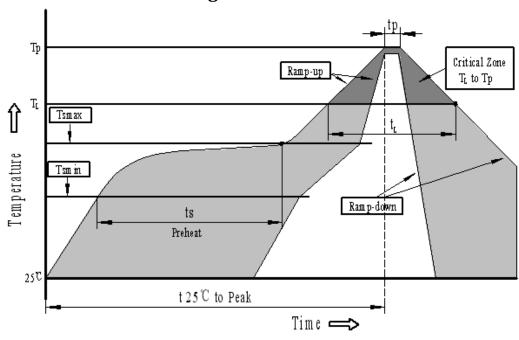


Reliability Testing

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Type of Test	Test Specifications		
High Temperature Test	The part shall be capable of withstanding a storage temperature is +80°C for 96 hours The part shall be capable of withstanding a storage		
Low Temperature Test	temperature is -30°C for 96 hours		
Humidity Test	40±2°C, 90~95% RH, 96 hours, then allowed to rest at room temperature for two hours		
	Total 5 cycles of the following		
Temperature Cycle Testing	+70°C +25°C +25°C -20°C 0.5hr 0.5 0.25 0.5 0.5 0.25 3hours		
	The part shall be subjected to a vibration cycle that is 10Hz in a period of 1 minute. Total peak amplitude shall be 1.52mm (9.3g).		
Vibration Test	The vibration test shall consist of 2 hours per plane in each three mutually perpendicular planes for a total time of 6 hours.		
Drop Test	Drop from a height of 75cm onto 4 cm thick wood board six times.		

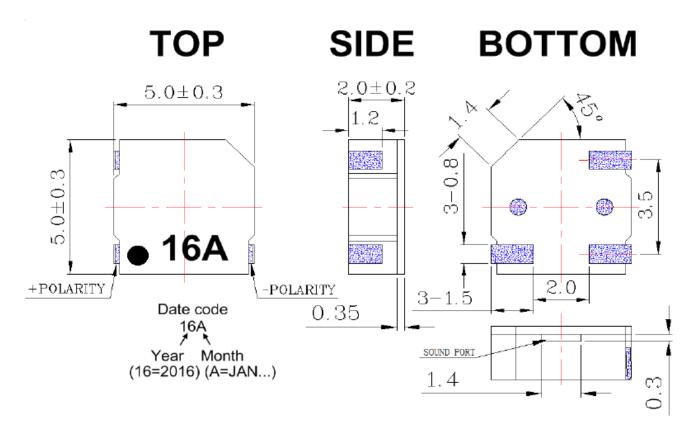
After each test, part shall meet specifications with an SPL variance of no more than ±10 dB

Recommended Reflow Soldering Procedure for Transducer



Profile Feature	Pb-Free Assembly
Average ramp-up rate (T _L to Tp)	3°C/second max.
Preheat	
-Temperature Min. (Ts _{min})	150°C
-Temperature Min. (Ts _{max})	200°C
-Temperature Min. (Ts)	60∼180 seconds
Tsmax to TL	
-Ramp-up Rate	3°C/second max.
Reflow	
- Temperature (T _L)	217°C
-Time (T _L)	60∼150 seconds
Peak temperature (Tp)	250°C+0/-5°C
Time within 5°Cof actual Peak temperature (Tp)	6 seconds max.
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

Transducer Dimensions



Evaluation Board Dimensions

